



Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Current	$I_{(AV)}$	35	A
Peak forward surge current	I_{FSM}	400	A
I2t Rating for Fusing ($t < 8.3ms$)	I2t	510	A2s
Typical Junction Capacitance(Note1)	CJ	85	pF
Typical Thermal Resistance (Note2)	$R_{\theta Jc}$	0.6	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55° 150	

NOTE:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 300mm*300mm*1.6mm cu plate heatsink.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R	I R				

Electrical Characteristic Curve

FIG.1-FORWARD CURRENT DERATING CURVE

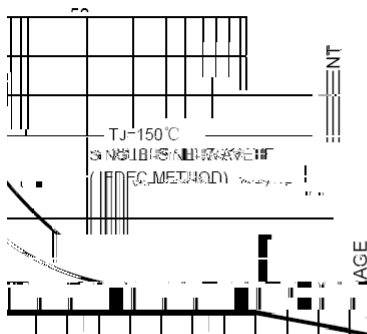
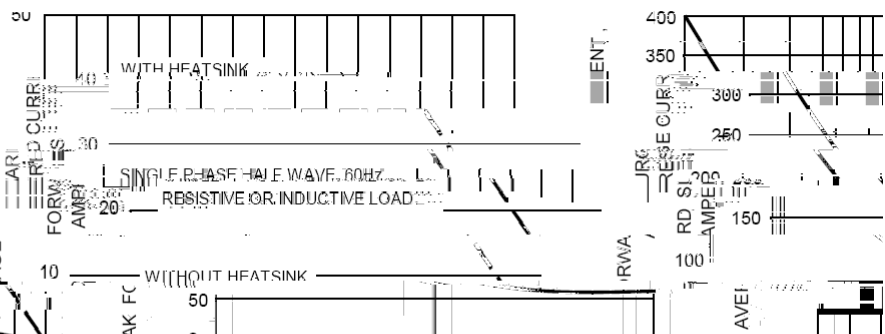
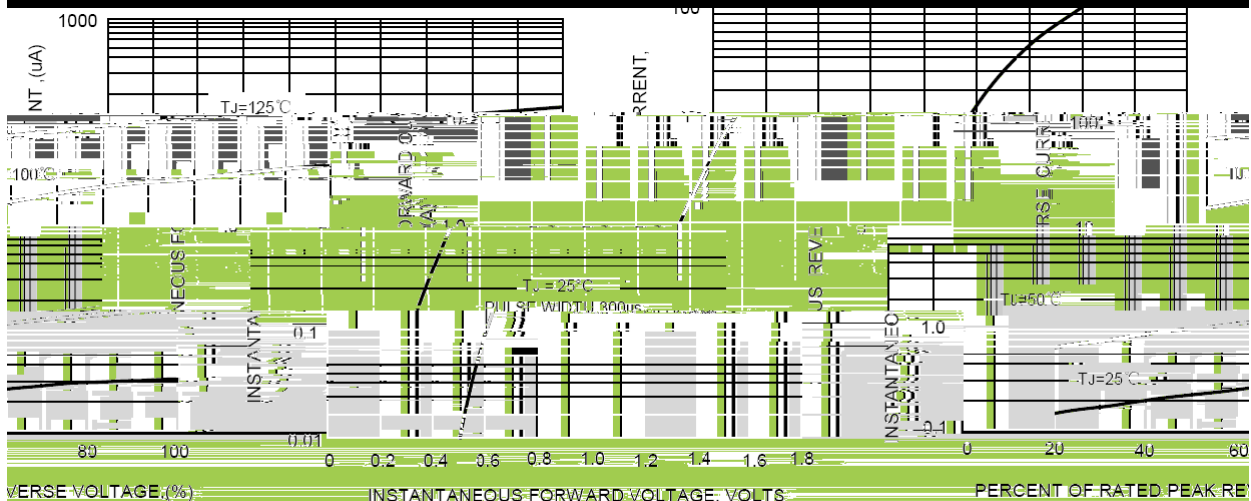
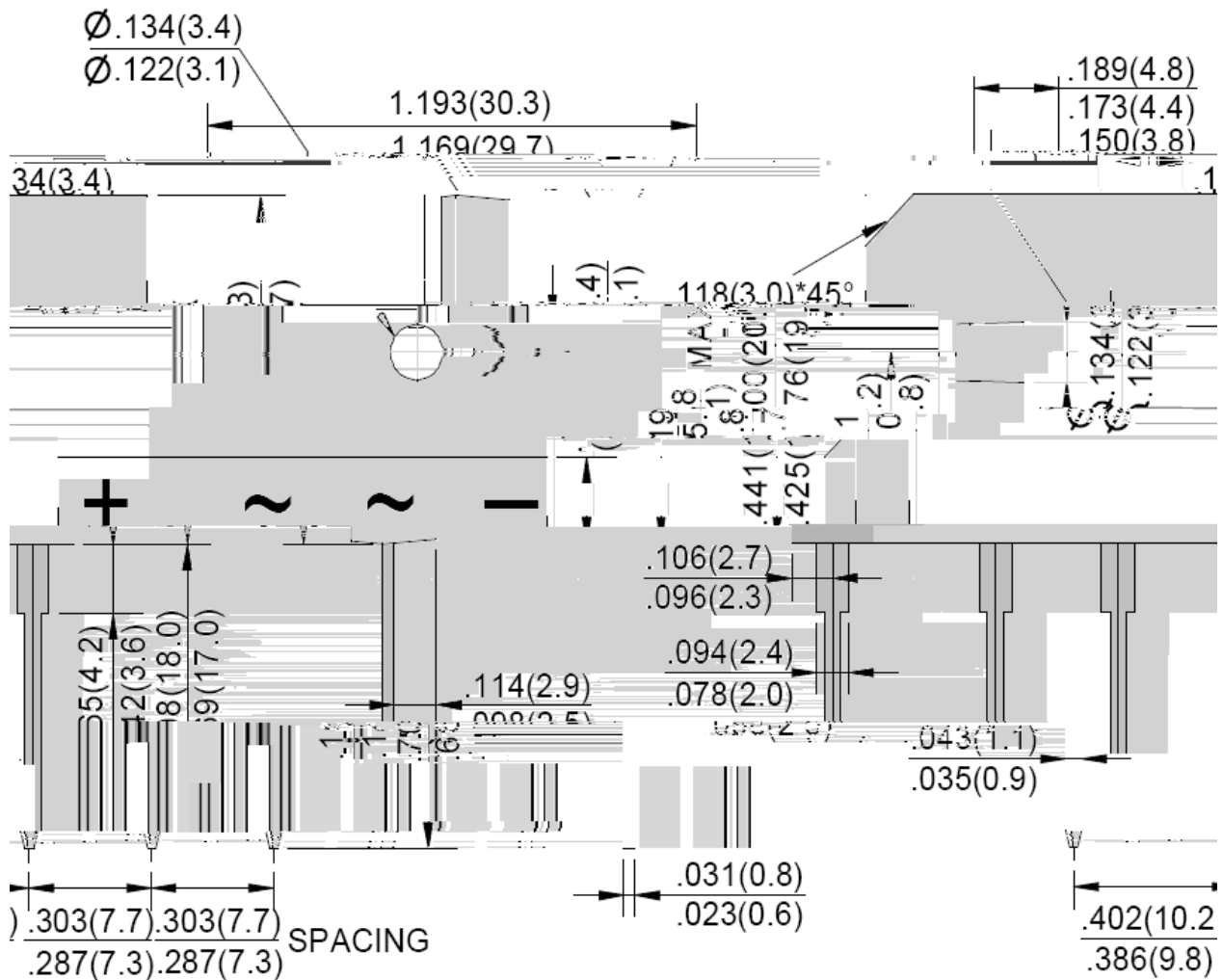


FIG.2-MAXMUN NON-REPETITIVE SURGE CURRENT

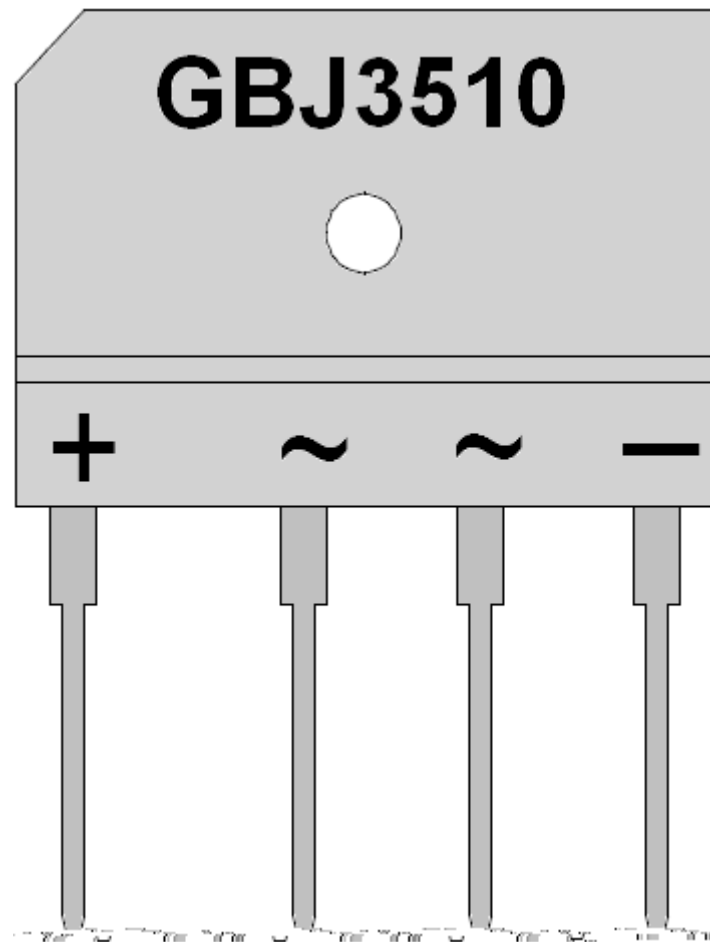


/ Package Dimensions

GBJ



/ Marking Instructions



GBJ3510
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() / Temperature Profile for Dip Soldering(Pb-Free)


б " X

1. 1. 25~150 °C, Time: 60~90sec;
2. 2. 255 °C, Duration: 5 °C 0.5sec;
3. 3. Cooling Speed: 2~10 °C /sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255 °C, Duration: 5 °C 0.5sec.
3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270 ± 5 °C, Time: 10 ± 1 sec. Temp.: 270 ± 5 °C Time: 10 ± 1 sec

/ Packaging SPEC.

“Q” T Y E / BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
GBJ	-	-	250	8	2000	-	315×135×48	330×285×215

“T” Y E / TUBE

Package Type	Units					Dimension (unit mm ³)		
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
GBJ	15	40	600	2	1200	471×42×10	500×190×105	525×210×245

/ Notices